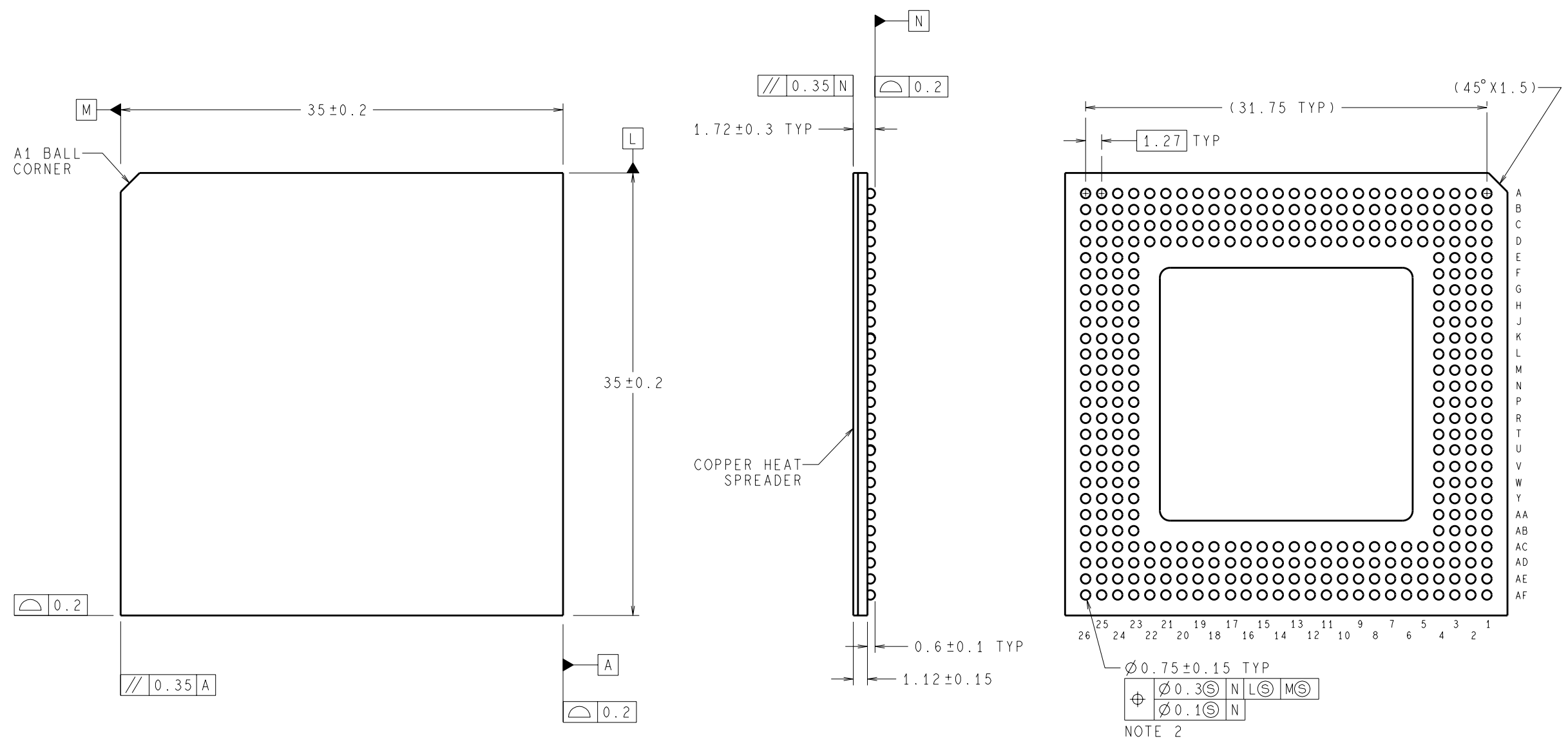


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12125	11/30/1998	TL/EL
B	REVISE TITLE; OVERALL THK'S 1.72 WAS 1.9; ADD TOTAL SUBS. THK'S 1.12±0.15; REMOVE DIM'S 0.38 MIN TYP & 0.75±0.15	146	09/01/2000	MS/AP



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
- DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
- REFERENCE JEDEC REGISTRATION MO-151, VARIATION -1.27, DATED JUNE 1997.

APPROVALS		DATE	National Semiconductor		
DRAWN T. LEQUANG		11/18/1998	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK. THANH LEQUANG		09/01/2000	EBGA, 35 X 35 X 1.72mm, 352 BALL, 1.27mm PITCH		
ENGR. CHK. ANINDYA PODDAR		09/01/2000			
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-UCJ352A	B
DO NOT SCALE DRAWING				SHEET 1 of 1	